

Please amend the paragraph beginning at page 10 line 17, and continuing to page 10, line 20, as follows:

Fig. 1 is a plan view schematically illustrating the constitution of an example embodiment of a sputtering apparatus including an example apparatus for removing particles in accordance with an embodiment of the present invention.

Please amend the paragraph beginning at page 21, line 18, and continuing to page 22, line 3, as follows:

~~In accordance with the present invention, since particles in the pressure buffer unit 12 are constantly collected by the charging means, 'device wafer processing' does not require to be stopped for 'particle collection process'. In addition, the ionizer 114 of the waiting-accommodation unit 113 is maintained at neutralization mode for neutralizing surface charge of the device wafers so that the change of mode is not required. As a result, the processing capability (the rate of operation) of the device is substantially improved.~~

Please amend the paragraph beginning at page 22, line 7, and continuing to page 22, line 6, as follows:

The load lock chamber and the charging means of the apparatus for removing particles according to the present invention will be described in more detail.

Please amend the paragraph beginning at page 23, line 12, and continuing to page 23, line 18, as follows:

~~In accordance with the present invention, special operations are not required for 'particle collection process'. Since wafers for particle collection used in the conventional art are not required, cost for purchasing wafers for particle~~

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